

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Previously Presented) A method of fabricating an integrated circuit, the method comprising:  
forming a barrier layer along lateral side walls and a bottom of a via aperture, the via aperture being configured to receive a via material that electrically connects a first conductive layer and a second conductive layer; and  
depositing a copper alloy via material in the via aperture to form a via, the copper alloy material including Zinc (Zn) or Silver (Ag) and at least one element for increasing grain size including Calcium (Ca) or Chromium (Cr).
2. (Previously Presented) The method of claim 1, wherein the copper alloy via material includes silver (Ag).
3. (Currently Amended) The method of claim 2, wherein the copper alloy via material includes ~~element with a characteristic for lowering resistivity is~~ Zinc (Zn).
4. (Currently Amended) The method of claim 1, wherein the copper alloy via material includes ~~element with a characteristic for lowering resistivity is~~ one atomic percent or less of Zinc (Zn) or Silver (Ag).
5. (Cancelled without prejudice)
6. (Previously Presented) The method of claim 1, wherein the copper alloy via material includes Chromium (Cr).
7. (Previously Presented) The method of claim ~~6~~1, wherein the element with a characteristic for increasing grain size is Calcium (Ca) or Chromium (Cr).

8. (Previously Presented) The method of claim 6, wherein the element with a characteristic for increasing grain size is one atomic percent or less of Chromium (Cr).
9. (Original) The method of claim 6, wherein the increased grain size is between 0.5 and 3  $\mu\text{m}$ .
10. (Previously Presented) A method of using ternary copper alloy to obtain a low resistance and large grain size interconnect or via, the method comprising:  
providing a first conductive layer over an integrated circuit substrate;  
providing a conformal layer section at a bottom and sides of a via aperture positioned over the first conductive layer to form a barrier separating the via aperture from the first conductive layer;  
filling the via aperture with a ternary copper alloy via material to form a ternary copper alloy via, the ternary copper alloy including at least one element for lowering resistivity and at least one of Chromium (Cr) or Calcium (Ca); and  
providing a second conductive layer over the ternary copper alloy via such that the ternary copper alloy via electrically connects the first conductive layer to the second conductive layer.
11. (Previously Presented) The method of claim 10, wherein the ternary copper alloy via material is at least 98 atomic percent copper.
12. (Currently Amended) The method of claim 11, wherein the ternary copper alloy via includes ~~element with a characteristic for lowering resistance~~ is Zinc (Zn), Silver (Ag), or Tin (Sn).
13. (Currently Amended) The method of claim 11, wherein the ternary copper alloy via includes ~~element with a characteristic for lowering resistance~~ is one atomic percent or less of ~~the ternary copper alloy via material~~ Chromium (Cr) or Calcium (Ca).

14. (Original) The method of claim 10, wherein the ternary copper alloy via material includes an element with a characteristic for increasing grain size of the ternary copper alloy via.

15. (Original) The method of claim 14, wherein the element with a characteristic for increasing grain size is Calcium (Ca) or Chromium (Cr).

16. (Original) The method of claim 14, wherein the element with a characteristic for increasing grain size is one atomic percent or less of the ternary copper alloy via material.

17. (Previously Presented) A method of forming a via in an integrated circuit, the method comprising:

depositing a first conductive layer;

depositing an etch stop layer over the first conductive layer;

depositing an insulating layer over the etch stop layer;

forming an aperture in the insulating layer and the etch stop layer;

providing a barrier material at a bottom and sides of the aperture to form a barrier layer;

filling the aperture with a ternary copper alloy via material to form a ternary copper alloy via including at least one of the following pairs of elements: Tin and Calcium; Tin and Chromium; Zinc and Chromium; Zinc and Calcium; Silver and Chromium; and Silver and Calcium; and

providing a second conductive layer over the ternary copper alloy via such that the ternary copper alloy via electrically connects the first conductive layer and the second conductive layer.

18. (Previously Presented) The method of claim 17, wherein the ternary copper alloy via material includes copper (Cu), tin (Sn), and Calcium (Ca).

19. (Original) The method of claim 17, wherein the ternary copper alloy via material includes copper (Cu), zinc (Zn), and chromium (Cr).

20. (Previously Presented) The method of claim 17, wherein the ternary copper alloy is CuAgCr, or CuSnCa.

21. (Original) The method of claim 17, wherein the ternary copper alloy via material includes an element with a characteristic for increasing grain size of the ternary copper alloy via.

22. (Previously Presented) The method of claim 17, wherein the ternary copper alloy via includes stuffed grain boundaries.

23. (Original) The method of claim 17, wherein the grain size of the ternary copper alloy via is 0.5 to 3  $\mu\text{m}$ .